Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.066”**



**.066”**

**Top Material: Al**

**Backside Material: Au**

**Base Pad Size: .0079” X .0079**

**Emitter Pad Size: .0079” X .0095”**

**Backside Potential: Collector**

**Mask Ref: CP753V-CT**

**APPROVED BY: DK DIE SIZE .066” X .066” DATE: 11/4/16**

**MFG: CENTRAL SEMI THICKNESS .008” P/N: CP753V-CZT953-CT**

#### DG 10.1.2

#### Rev B, 7/19/02